



Modified Form PTO/SB/08A

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Complete If Known

Application Number	10/026,469
Filing Date	December 27, 2001
First Named Inventor	Miller
Group Art Unit	2835
Examiner Name	G. Tolin
Attorney Docket No.	2026.0030000

Sheet	1	of	1
-------	---	----	---

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant	Publication Date	Relevant Portions
		Number	Kind Code ²			
GPT	1	2002/0004320	A1	Pedersen et al.	1/10/2002	
GPT	2	4000509		Jarvela	12/28/1976	
GPT	3	4561040		Eastman et al.	12/24/1985	
GPT	4	4820976		Brown	4/11/1989	
GPT	5	4860444		Herrell et al.	8/29/1989	
GPT	6	5102343		Knight et al.	4/7/1992	
GPT	7	5198753		Hamburgen	3/30/1993	
GPT	8	5550482		Sano	8/27/1996	
GPT	9	5834946		Albrow et al.	11/10/1998	
GPT	10	6033935		Dozier, II et al.	3/7/2000	
GPT	11	6078500		Beaman et al.	6/20/2000	
GPT	12	6085831		DiGiacomo et al.	7/11/2000	
GPT	13	6468098	B1	Eldridge	10/22/2002	

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document			Name of Patentee or Applicant	Publication Date	Relevant Portions	T ⁶
		Office ³	Number ⁴	Kind Code ⁵				
GPT	14	WO	98/52224		Pedersen et al.	11/19/1998		
GPT	15	WO	01/131130		Eldridge	2/22/2001		

OTHER PRIOR ART – NONPATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ⁶
GPT	16	"Cooling System For Semiconductor Modules," IBM Technical Disclosure Bulletin, vol. 26, no. 3B (August 1983), pg. 1548	

Examiner Signature	<i>GPT Tolin</i>	Date Considered	4/11/03
-----------------------	------------------	--------------------	---------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶Applicant is to place a check mark here if English language Translation is attached.



FORM PTO-1449

INFORMATION DISCLOSURE STATEMENTATTY. DOCKET NO.
2026.0030000APPLICATION NO.
10/026,469APPLICANT
Charles A. MILLERFILING DATE
December 27, 2001GROUP
2835

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	FILING DATE
	AA1	10/026,471		Charles A. Miller			12/27/2001
	AB1	4,000,509	12/1976	Jarvela	357	01	03/31/1975
	AC1	4,245,273	01/1981	Feinberg et al.	361	382	06/29/1979
	AD1	4,361,040	12/1985	Eastman et al.	361	385	07/12/1981
	AE1	4,839,774	06/1989	Hamburgen	361	382	01/25/1988
	AF1	5,650,914	07/1997	DiStefano et al.	361	704	08/12/1996
	AG1	5,917,707	06/1999	Khandros et al.	361	776	11/15/1994
	AH1	6,064,213	05/2000	Khandros et al.	324	754	01/15/1997
	AI1	6,085,831	07/2000	DiGiacomo et al.	165	104.33	03/03/1999
	AJ1	6,184,065	02/2001	Smith et al.	438	117	03/25/1999
	AK1	6,255,126 B1	07/2001	Mathieu et al.	438	15	12/02/1998
	AL1	6,451,709	09/2002	Hembree	438	759	02/23/200

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION
	AL1						Yes No
	AM1						Yes No
	AN1						Yes No
	AO1						Yes No
	AP1						Yes No

OTHER (Including Author, Title, Date, Pertinent Pages, etc.)

NO COPY	AR	1	International Application Published Under the Patent Cooperation Treaty (PCT), "Lithographic Contact Elements", Mathieu, Gaetan L., International Publication Number WO 00/33089, Publication Date: June 8, 2000
GPT	AS	1	Advanced Electronic Packaging - With Emphasis on Multichip Modules, edited by William D. Brown, "13.5 Competitive Mainframe Packaging Examples," pages 547- 550, Institute of Electrical and Electronics Engineers (1999)
GPT	AT	1	Electronic Packaging and Interconnection Handbook, Editor-in Chief by Charles A. Harper, "2.7 High Heat-Load Cooling," pages 2.57-2.66, Third Edition (2000), McGraw-Hill

EXAMINER

GPT tolu

DATE CONSIDERED 4/11/03

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609.
Draw line through citation if not in conformance and not considered. Include copy of this form with
next communication to Applicant.